



3D Packaging and Integration Japan TC Chapter Meeting Summary and Minutes

Japan Standards Spring 2018 Meetings

Monday, May 21, 2018, 13:30–16:30

SEMI Japan office, Tokyo, Japan

TC Chapter Announcements

Next TC Chapter Meeting

Monday, October 15, 2018, Time to be decided

SEMI Japan office, Tokyo, Japan

Table 1 Meeting Attendees

Italics indicate virtual participants

Co-Chairs: Kazunori Kato (AiT), Masahiro Tsuruya (iNEMI), Haruo Shimamoto (AIST)

SEMI Staff: Chie Yanagisawa (SEMI Japan)

<i>Company</i>	<i>Last</i>	<i>First</i>	<i>Company</i>	<i>Last</i>	<i>First</i>
AIST	Shimamoto	Haruo	Shin-Etsu Polymer	Fukunaga	Tsukasa
Asahi Glass	Takahashi	Mamoru	Shin-Etsu Polymer	Shida	Hiroyuki
FUJIFILM	Sawano	Mitsuru	SUMCO	Nakai	Tetsuya
iNEMI	Tsuruya	Masahiro	Tokyo Seimitsu	Chiba	Kiyotaka
Keyence	Tsunobuchi	Hirokazu	SEMI Japan	Yanagisawa	Chie

Table 2 Leadership Changes

<i>WG/TF/SC/TC Name</i>	<i>Previous Leader</i>	<i>New Leader</i>
Thin Chip Handling TF <i>*This leadership change was made at the TC Chapter meeting on September 13, 2017, but the record was missed on the CER of that meeting.</i>	Haruo Shimamoto (AIST) Hideki Suzuki (Shin-Etsu Polymer)	Haruo Shimamoto (AIST) remains as the leader Hideki Suzuki stepped down from the leader.

Table 3 Committee Structure Changes

<i>Previous WG/TF/SC Name</i>	<i>New WG/TF/SC Name or Status Change</i>
None	

Table 4 Ballot Results

<i>Document #</i>	<i>Document Title</i>	<i>Committee Action</i>
6352	Line Item Revision to SEMI G64-96 (Reapproved 0811) “Specification for Full-Plated Integrated Circuit Leadframes (Au, Ag, Cu, Ni, Pd/Ni, Pd)”	/
Line Item 1	Change section title to meet the requirement which is specified section 3.2 of Procedure Manual	Passed as balloted
6353	Reapproval of SEMI G94-0113: Specification for Coin-Stack Type Tape Frame Shipping Container for 300 mm Wafer	Passed as balloted

Note 1: **Passed** ballots and line items will be submitted to the ISC Audit & Review Subcommittee for procedural review.

Note 2: **Failed** ballots and line items were returned to the originating task forces for re-work and re-balloting or abandoning.

Table 5 Activities Approved by the GCS prior to the Originating TC Chapter meeting

#	Type	SC/TF/WG	Details
6352	Ballot submission	3D Packaging & Integration 5Year Review TF	Line Item Revision to SEMI G64-96 (Reapproved 0811) "Specification for Full-Plated Integrated Circuit Leadframes (Au, Ag, Cu, Ni, Pd/Ni, Pd)"
6353	Ballot submission	3D Packaging & Integration 5Year Review TF	Reapproval of SEMI G94-0113: Specification for Coin-Stack Type Tape Frame Shipping Container for 300 mm Wafer

Table 6 Authorized Activities

Listing of all revised or new SNARF(s) approved by the Originating TC Chapter.

#	SC/TF/WG	Details
None		

Note 1: SNARFs and TFOFs are available for review on the SEMI Web site at:

<http://downloads.semi.org/web/wstdsbal.nsf/TFOFSNARF>

Table 7 Authorized Ballots

#	When	TF	Details
#6224	Cycle 6	3D Packaging & Integration 5Year Review TF	Revision to SEMI G11-88 (Reapproved 0811): "Recommended Practice for RAM Follower Gel Time and Spiral Flow of Thermal Setting Molding Compounds" with non-conforming title change to "Practice for RAM Follower Gel Time and Spiral Flow of Thermal Setting Molding Compounds"
#6233	Cycle 6	3D Packaging & Integration 5Year Review TF	Line Item Revision to SEMI G29-1296E (Reapproved 0811): Test Method for Trace Contaminants in Molding Compounds
#6230	Cycle 6	3D Packaging & Integration 5Year Review TF	Revision to SEMI G43-87 (Reapproved 0811): Test Method for Junction-to-Case Thermal Resistance Measurements of Molded Plastic Packages
#6094	Cycle 6	3D Packaging & Integration 5Year Review TF	Revision to SEMI G45-93: "Recommended Practice for Flash Characteristics of Thermosetting Molding Compounds", with title change to "Practice for Flash Characteristics of Thermosetting Molding Compounds"
#6232	Cycle 6	3D Packaging & Integration 5Year Review TF	Revision to SEMI G55-93 (Reapproved 0811): Test Method for Measurement of Silver Plating Brightness
#6167	Cycle 6	3D Packaging & Integration 5Year Review TF	Line Item Revision to SEMI G73-0997 (Reapproved 0811) "Test Method for Pull Strength for Wire Bonding"

Table 8 SNARF(s) Granted a One-Year Extension

#	TF	Title	Expiration Date
None			

Table 9 SNARF(s) Abolished

#	TF	Title
#6223	3D Packaging & Integration 5Year Review TF	Revision to SEMI G4-0302 (Reapproved 0811): Specification for Integrated Circuit Leadframe Materials Used in the Production of Stamped Leadframes
#6154	3D Packaging & Integration 5Year Review TF	Line Item Revision to SEMI G10-96 (Reapproved 0811): “Standard Method for Mechanical Measurement of Plastic Package Leadframes” with non-conforming title change to “Test Method for Mechanical Measurement of Plastic Package Leadframes”
#6225	3D Packaging & Integration 5Year Review TF	Revision to SEMI G13-88 (Reapproved 0811): “Standard Test Method for Expansion Characteristics of Molding Compounds” with non-conforming title change to “Test Method for Expansion Characteristics of Molding Compounds”
#6226	3D Packaging & Integration 5Year Review TF	Revision to SEMI G15-93 (Reapproved 0811): “Standard Test Method for Differential Scanning Calorimetry of Molding Compounds” with non-conforming title change to “Test Method for Differential Scanning Calorimetry of Molding Compounds”
#6030	3D Packaging & Integration 5Year Review TF	Revision to SEMI G20-96: Specification for Lead Finishes for Plastic Packages (Active Devices Only)
#6227	3D Packaging & Integration 5Year Review TF	Revision to SEMI G24-89 (Reapproved 0811): Test Method for Measuring the Lead-to-Lead and Loading Capacitance of Package Leads
#6228	3D Packaging & Integration 5Year Review TF	Revision to SEMI G25-89 (Reapproved 0811): Test Method for Measuring the Resistance of Package Leads
#6229	3D Packaging & Integration 5Year Review TF	Revision to SEMI G28-0997 (Reapproved 0811): Specification for Leadframes for Plastic Molded S.O. Packages
#6093	3D Packaging & Integration 5Year Review TF	Revision to SEMI G31-0997: Test Method for Determining the Abrasive Characteristics of Molding Compounds
#6095	3D Packaging & Integration 5Year Review TF	Revision to SEMI G49-93: Specification for Plastic Molding Preforms
#6231	3D Packaging & Integration 5Year Review TF	Revision to SEMI G51-90 (Reapproved 0811): Specification for Plastic Molded (Metric) Quad Flat Pack Leadframes
#6156	3D Packaging & Integration 5Year Review TF	Line Item Revision to SEMI G70-0996 (Reapproved 0811): “Standard for Equipment and Leadframe Fixtures for Measurement of Plastic Package Leadframes” with non-conforming title change to “Specification for Equipment and Leadframe Fixtures for Measurement of Plastic Package Leadframes”
#6152	3D Packaging & Integration 5Year Review TF	Line Item Revision to SEMI G93-0412: “Measurement Method for Solder Sphere Size for Ball Grid Array Package” with non-conforming title change to “Test Method for Solder Sphere Size for Ball Grid Array Package”
#5881	3D Packaging & Integration 5Year Review TF	Reapproval of SEMI G83-0912: SPECIFICATION FOR BAR CODE MARKING OF PRODUCT PACKAGES *Three years have passed since its initial approval. A new SNARF for Revision to SEMI G83-0912 is to be proposed.
#5836	Thin Chip Handling TF	New Standard: Test Method for Adhesive Strength for Adhesive Tray Used for Thin Chip Handling *Three years have passed since its initial approval. A new SNARF about the same topic is to be proposed.

Table 10 Standard(s) to receive Inactive Status

Standard Designation	Title
SEMI G4-0302 (Reapproved 0811)	Specification for Integrated Circuit Leadframe Materials Used in the Production of Stamped Leadframes
SEMI G10-96 (Reapproved 0811)	Standard Method for Mechanical Measurement of Plastic Package Leadframes

<i>Standard Designation</i>	<i>Title</i>
SEMI G13-88 (Reapproved 0811)	Standard Test Method for Expansion Characteristics of Molding Compounds
SEMI G15-93 (Reapproved 0811)	Standard Test Method for Differential Scanning Calorimetry of Molding Compounds
SEMI G20-96	Specification for Lead Finishes for Plastic Packages (Active Devices Only)
SEMI G24-89 (Reapproved 0811)	Test Method for Measuring the Lead-to-Lead and Loading Capacitance of Package Leads
SEMI G25-89 (Reapproved 0811)	Test Method for Measuring the Resistance of Package Leads
SEMI G28-0997 (Reapproved 0811)	Specification for Leadframes for Plastic Molded S.O. Packages
SEMI G31-0997	Test Method for Determining the Abrasive Characteristics of Molding Compounds
SEMI G49-93	Specification for Plastic Molding Preforms
SEMI G51-90 (Reapproved 0811)	Specification for Plastic Molded (Metric) Quad Flat Pack Leadframes
SEMI G70-0996 (Reapproved 0811)	Standard for Equipment and Leadframe Fixtures for Measurement of Plastic Package Leadframes
SEMI G93-0412	Measurement Method for Solder Sphere Size for Ball Grid Array Package

Table 11 New Action Items

<i>Item #</i>	<i>Assigned to</i>	<i>Details</i>
20180521-01	SEMI Staff	to confirm when the virtual meeting launches
20180521-02	SEMI Staff	to send a new SNARF for New Standard: “Test method for Adhesive Strength for Adhesive Tray Used for Thin Chip Handling” for TC member two weeks review.
20180521-03	SEMI Staff	to request this SNARF for New Standard: “Test method for Adhesive Strength for Adhesive Tray Used for Thin Chip Handling” and the ballot submission for GCS approval
20180521-04	SEMI Staff	to send a new SNARF for Revision to SEMI G83-0912 “Specification for Bar Code Marking of Product Packages” and Withdrawal of SEMI G83.1-0912 “Specification for Bar Code Marking of Product Packages” for TC member two weeks review.
20180521-05	SEMI Staff	to request this SNARF for Revision to SEMI G83-0912 “Specification for Bar Code Marking of Product Packages” and Withdrawal of SEMI G83.1-0912 “Specification for Bar Code Marking of Product Packages” and the ballot submission for GCS approval

Table 12 Previous Meeting Action Items

<i>Item #</i>	<i>Assigned to</i>	<i>Details</i>
20180205-01	Chie Yanagisawa (SEMI Japan)	To look into the current affiliate status of Standards members. -> OPEN
20180205-02	Masahiro Tsuruya (iNEMI)	To prepare a new SNARF for SEMI G83 in order to propose it at the next 3D Packaging & Integration Japan TC Chapter meeting. -> CLOSE, the SNARF to be proposed at this meeting
20180205-03	Haruo Shimamoto (AIST)	To review SEMI G63 to decide for the next action to it by the next 3D Packaging & Integration Japan TC Chapter meeting. -> OPEN
20180205-04	Kazunori Kato (AiT)	To invite the related companies to SEMI E142 revision activity. -> OPEN, to ask about it to Kazunori Kato (AiT)
20170913-04	Thin Chip Handling TF leaders	To prepare the proposal of #5836 ballot. -> OPEN

1 Welcome, Reminders, and Introductions

Masahiro Tsuruya (iNEMI) called the meeting to order at 13:30. The meeting reminders on antitrust issues, intellectual property issues and holding meetings with international attendance were reviewed. Attendees introduced themselves.

Attachment: 01_Required_Elements_Reg_20150327_E+J

2 Review of Previous Meeting of 3D Packaging & Integration Japan TC Chapter

2.1 Review and Approval of Previous Meeting Minutes of 3D Packaging & Integration Japan TC Chapter.

The TC Chapter reviewed the minutes of the previous meeting.

Motion:	To approve the previous meeting minutes of the 3D Packaging & Integration Japan TC Chapter on February 5, 2018 as written.
By / 2nd:	Haruo Shimamoto (AIST) / Mamoru Takahashi (Asahi Glass)
Discussion:	None
Vote:	7 in favor and 0 opposed. Motion passed.

Attachment: 02_20180205_3DP&I-Japan_Minutes_Final

2.2 Review of Action Items from Previous 3D Packaging & Integration Japan TC Chapter meetings

Item #	Assigned to	Details
20180205-01	Chie Yanagisawa (SEMI Japan)	To look into the current affiliate status of Standards members. -> OPEN
20180205-02	Masahiro Tsuruya (iNEMI)	To prepare a new SNARF for SEMI G83 in order to propose it at the next 3D Packaging & Integration Japan TC Chapter meeting. -> CLOSE, the SNARF to be proposed at this meeting
20180205-03	Haruo Shimamoto (AIST)	To review SEMI G63 to decide for the next action to it by the next 3D Packaging & Integration Japan TC Chapter meeting. -> OPEN
20180205-04	Kazunori Kato (AiT)	To invite the related companies to SEMI E142 revision activity. -> OPEN, to ask about it to Kazunori Kato (AiT)
20170913-04	Thin Chip Handling TF leaders	To prepare the proposal of #5836 ballot. -> OPEN

3 Liaison Reports

3.1 3D Packaging & Integration North America (NA) TC Chapter

Chie Yanagisawa (SEMI Japan) reported the activity status of 3D Packaging & Integration North America TC Chapter as attached. Of note:

- #6332: New Standard, Specification for Panel Substrate Characteristics for Fan-Out Panel Level Packaging (FO-PLP) Applications
 - By FO-PLP Panel TF
 - TC Member Review took place between 12/20/2017 and 01/03/2018
 - SNARF was approved by GCS on 01/11/2018
 - Ballot draft has been reviewed by the task force members.
- #6075: New Standard, Guide for Describing Glass and Quartz Based Material for Use in 3DS-IC Process
 - By 3DP&I Bonded Wafer Stacks TF

- Revision to SNARF title and scope. TC Member Review took place between 03/13/2018 and 03/26/2018
- #5173: New Standard, Guide for Describing Silicon Wafers for Use in a 300 mm 3DS-IC Wafer Stack
 - No industry push, Activity discontinued

Attachment: 03_NA 3DP&I Liaison Report Apr2018 v1.1

3.2 3D Packaging & Integration Taiwan TC Chapter

Chie Yanagisawa (SEMI Japan) reported for the 3D Packaging & Integration Taiwan TC Chapter based on the report as attached. Of note:

- #5800A: New Standards: Guide for Wafer Edge Trimming for 3DS-IC Process
 - Passed with editorial change

Attachment: 04_3D P&I TW Liaison Report_20180510

3.3 SEMI Staff Report

Chie Yanagisawa (SEMI Japan) gave the SEMI Staff Report. Of note:

- SEMI Global 2018 Calendar of Events
- Global Standards Meeting Schedule
- NA Standards Spring 2018 Meetings
- 2018 Critical Dates for SEMI Standards Ballots
- A&R Ballot Review
- SEMI Standards Publications, New Standards Published during the last 12 months
- Japan Regional Standards Committee (JRSC) Topics – Standards Awards
- SEMI Japan Newsletter – Standards topics

Action Item: 20180521-01, SEMI Staff to confirm when the virtual meeting launches

Attachment: 05_SEMI Staff Report 20180515_0.2

4 Ballot Review

NOTE 1: TC Chapter adjudication on ballots reviewed is detailed in the Audits & Review (A&R) Subcommittee Forms for procedural review. The A&R forms are available as attachments to these minutes. The attachment number for each balloted document is provided under each ballot review section below.

4.1 Document #6352: Line Item Revision to SEMI G64-96 (Reapproved 0811) “Specification for Full-Plated Integrated Circuit Leadframes (Au, Ag, Cu, Ni, Pd/Ni, Pd)”

4.1.1 Line Item 1: Change section title to meet the requirement which is specified section 3.2 of Procedure Manual

4.2 Document #6353: Reapproval of SEMI G94-0113: Specification for Coin-Stack Type Tape Frame Shipping Container for 300 mm Wafer

Attachment: 06_#6352_G64_LineItemLetterBallotReviewSheet,
07_#6353_G94_Reapproval_LetterBallotReviewSheet

5 Subcommittee and Task Force Reports

5.1 GCS Report

The Japan TC Chapter sent the following two documents for GCS approval for ballot submission. Authorized on March 9, 2018

- 6352: Line Item Revision to SEMI G64-96 (Reapproved 0811) “Specification for Full-Plated Integrated Circuit Leadframes (Au, Ag, Cu, Ni, Pd/Ni, Pd)”
- 6353: Reapproval of SEMI G94-0113: Specification for Coin-Stack Type Tape Frame Shipping Container for 300 mm Wafer

5.2 JA 450mm Assembly and Test Die Preparation Task Force

Chie Yanagisawa (SEMI Japan) conveyed the message that Sumio Masuchi (DISCO), the TF co-leader, reported that there is no update.

5.3 3D Packaging & Integration 5 Year Review Task Force

Masahiro Tsuruya (iNEMI), the TF co-leader, reported that the details are provided in “Old Business” and “New Business” of this meeting later.

5.4 Thin Chip Handling Task Force

Chie Yanagisawa reported Document #5836 passed three years since its initial approval, so it went inactive status. If this activity continues, a new SNARF is required. Haruo Shimamoto (AIST) intended to revise SNARF #5836, so to go to prepare for a new SNARF for this activity.

The title is New Standard: Test method for Adhesive Strength for Adhesive Tray Used for Thin Chip Handling

The TC Chapter reviewed the SNARF draft and Haruo Shimamoto, the TF co-leader, showed his plan for this document as follows.

- The SNARF draft to be submitted and to be distributed to the global TC members for two weeks review
- GCS approval to be requested for this new SNARF
- GCS approval to be requested for Ballot submission of this document

Action Item: 20180521-02, SEMI Staff to send a new SNARF for New Standard: “Test method for Adhesive Strength for Adhesive Tray Used for Thin Chip Handling” for TC member two weeks review.

Action Item: 20180521-03, SEMI Staff to request this SNARF for New Standard: “Test method for Adhesive Strength for Adhesive Tray Used for Thin Chip Handling” and the ballot submission for GCS approval

Attachment: 08_NewSNARF(Draft)_ThinChipHandlingTF_TEST

5.5 3D Packaging & Integration Steering Group

Masahiro Tsuruya (iNEMI), the co-leader, reported as attached. The previous meeting was held on December 15, 2017. The discussion topics at the meeting are as follows:

- Discussion on Ballot draft #6332 by FO-PLP Panel TF under the North America TC Chapter
- TF Opportunities discussion

Attachment: 09_3D-PKG SWG Meeting Minutes - 2018-03-12

5.6 (PI&C liaison) Fan-Out Panel Level Packaging (FO-PLP) Panel FOUP TF

Nobuyuki Shida (Shin-Etsu Polymer) reported that the TF formation was approved by the PI&C Japan TC Chapter at the meeting on April 26, 2018.

6 Old Business

6.1 Project Period Review

None

6.2 5 Year Review Check

6.2.1 Withdrawal of SNARFs and getting the documents to receive inactive status

- #6223: SEMI G4-0302 (Reapproved 0811): Specification for Integrated Circuit Leadframe Materials Used in the Production of Stamped Leadframes
- #6154: SEMI G10-96 (Reapproved 0811): Standard Method for Mechanical Measurement of Plastic Package Leadframes
- #6225: SEMI G13-88 (Reapproved 0811): Standard Test Method for Expansion Characteristics of Molding Compounds
- #6226: SEMI G15-93 (Reapproved 0811): Standard Test Method for Differential Scanning Calorimetry of Molding Compounds
- #6030: SEMI G20-96: Specification for Lead Finishes for Plastic Packages (Active Devices Only)
- #6227: SEMI G24-89 (Reapproved 0811): Test Method for Measuring the Lead-to-Lead and Loading Capacitance of Package Leads
- #6228: SEMI G25-89 (Reapproved 0811): Test Method for Measuring the Resistance of Package Leads
- #6229: SEMI G28-0997 (Reapproved 0811): Specification for Leadframes for Plastic Molded S.O. Packages
- #6093: SEMI G31-0997: Test Method for Determining the Abrasive Characteristics of Molding Compounds
- #6095: SEMI G49-93: Specification for Plastic Molding Preforms
- #6231: SEMI G51-90 (Reapproved 0811): Specification for Plastic Molded (Metric) Quad Flat Pack Leadframes
- #6156: SEMI G70-0996 (Reapproved 0811): Standard for Equipment and Leadframe Fixtures for Measurement of Plastic Package Leadframes
- #6152: SEMI G93-0412: Measurement Method for Solder Sphere Size for Ball Grid Array Package

Masahiro Tsuriya (iNEMI) addressed the topic to the committee. He proposed withdrawal of the 13 SNARFs above as follows.

Motion:	To withdrawal these 13 SNARFs
By / 2nd:	Masahiro Tsuriya (iNEMI) / Mamoru Takahashi (Asahi Glass)
Discussion:	None
Vote:	8 in favor and 0 opposed. Motion passed.

The TC Chapter also confirmed that these 13 standards received inactive status.

6.2.2 SEMI G63-95 (Reapproved 0811): Test Method for Measurement of Die Shear Strength

Haruo Shimamoto (AIST) said that he will report what to do for this document at the next TC Chapter meeting.

6.3 Possibility of Cooperation with JEITA

There is no report at this meeting.

6.4 Discussion on the SNARF for Revision to SEMI E142 Substrate Mapping by Information & Control (I&C) Korea TC Chapter

There is no report. This section could be closed because there is little interest among the members in this TC Chapter.

7 New Business

7.1 Proposal for New SNARF

7.1.1 SNARF for: Revision to SEMI G83-0912 “Specification for Bar Code Marking of Product Packages” and Withdrawal of SEMI G83.1-0912 “Specification for Bar Code Marking of Product Packages”

Hirokazu Tsunobuchi (Keyence) explained the SNARF draft and the TC Chapter reviewed it.

- Rationale:
 - SEMI G83-0912 and G83.1-0912 is due for 5 Year Review. SEMI G83 is primary standard, and SEMI G83.1 subordinate standard which adds two-dimensional barcode symbol to G83 primary document. Therefore, most contents are duplicate among these two standards. So, Revision to G83-0912 and the withdrawal of G83.1-0912 are proposed based on the Regulations and this new SNARF draft is created.
- Scope:
 - The redundant parts of G83-0912 and G83.1-0912 are merged as Revision to G83-0912. Simultaneously, G83.1-0912 is withdrawn.
- Intercommittee Ballot
 - Traceability

He showed his plan for this document as follows.

- The SNARF draft to be submitted and to be distributed to the global TC members for two weeks review
- GCS approval to be requested for this new SNARF
- GCS approval to be requested for Ballot submission of this document

Action Item: 20180521-04, SEMI Staff to send a new SNARF for Revision to SEMI G83-0912 “Specification for Bar Code Marking of Product Packages” and Withdrawal of SEMI G83.1-0912 “Specification for Bar Code Marking of Product Packages” for TC member two weeks review.

Action Item: 20180521-05, SEMI Staff to request this SNARF for Revision to SEMI G83-0912 “Specification for Bar Code Marking of Product Packages” and Withdrawal of SEMI G83.1-0912 “Specification for Bar Code Marking of Product Packages” and the ballot submission for GCS approval

7.2 Proposal for Ballot Submission

7.2.1 #6224: Revision to Revision to SEMI G11-88 (Reapproved 0811): “Recommended Practice for RAM Follower Gel Time and Spiral Flow of Thermal Setting Molding Compounds” with non-conforming title change to “Practice for RAM Follower Gel Time and Spiral Flow of Thermal Setting Molding Compounds”

7.2.2 #6233: Line Item Revision to SEMI G29-1296E (Reapproved 0811): Test Method for Trace Contaminants in Molding Compounds

7.2.3 #6230: Revision to SEMI G43-87 (Reapproved 0811): Test Method for Junction-to-Case Thermal Resistance Measurements of Molded Plastic Packages



7.2.4 #6094: Revision to SEMI G45-93: “Recommended Practice for Flash Characteristics of Thermosetting Molding Compounds”, with title change to “Practice for Flash Characteristics of Thermosetting Molding Compounds”

7.2.5 #6232: Revision to SEMI G55-93 (Reapproved 0811): Test Method for Measurement of Silver Plating Brightness

7.2.6 #6167: Line Item Revision to SEMI G73-0997 (Reapproved 0811) “Test Method for Pull Strength for Wire Bonding”

Motion:	To approve ballot submission of these six documents above.
By / 2nd:	Masahiro Tsuriya (iNEMI) / Tsukasa Fukunaga (Shin-Etsu Polymer)
Discussion:	None
Vote:	7 in favor and 0 opposed. Motion passed.

8 Next Meeting and Adjournment

The next meeting is scheduled for Monday, October 15, 2018 (the time to be decided) at SEMI Japan office. See <http://www.semi.org/en/events> for the current list of meeting schedules.

Having no further business, a motion was made to adjourn. Adjournment was at 16:30.



Respectfully submitted by:

Chie Yanagisawa

Manager

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Minutes tentatively approved by:

Kazunori Kato (AiT), Co-chair	MMDD, 2018
Masahiro Tsuruya (iNEMI), Co-chair	July 3, 2018
Haruo Shimamoto (ASIT), Co-chair	MMDD, 2018

Table 13 Index of Available Attachments#1

<i>Title</i>	<i>Title</i>
01_Required_Elements_Reg_20150327_E+J	06_#6352_G64_LineItemLetterBallotReviewSheet
02_20180205_3DP&I-Japan_Minutes_Final	07_#6353_G94_Reapproval_LetterBallotReviewSheet
03_NA 3DP&I Liaison Report Apr2018 v1.1	08_NewSNARF(Draft)_ThinChipHandlingTF_TEST
04_3D P&I TW Liaison Report_20180510	09_3D-PKG SWG Meeting Minutes - 2018-03-12
05_SEMI Staff Report 20180515_0.2	

#1 Due to file size and delivery issues, attachments must be downloaded separately. A .zip file containing all attachments for these minutes is available at www.semi.org. For additional information or to obtain individual attachments, please contact [SEMI Staff Name] at the contact information above.